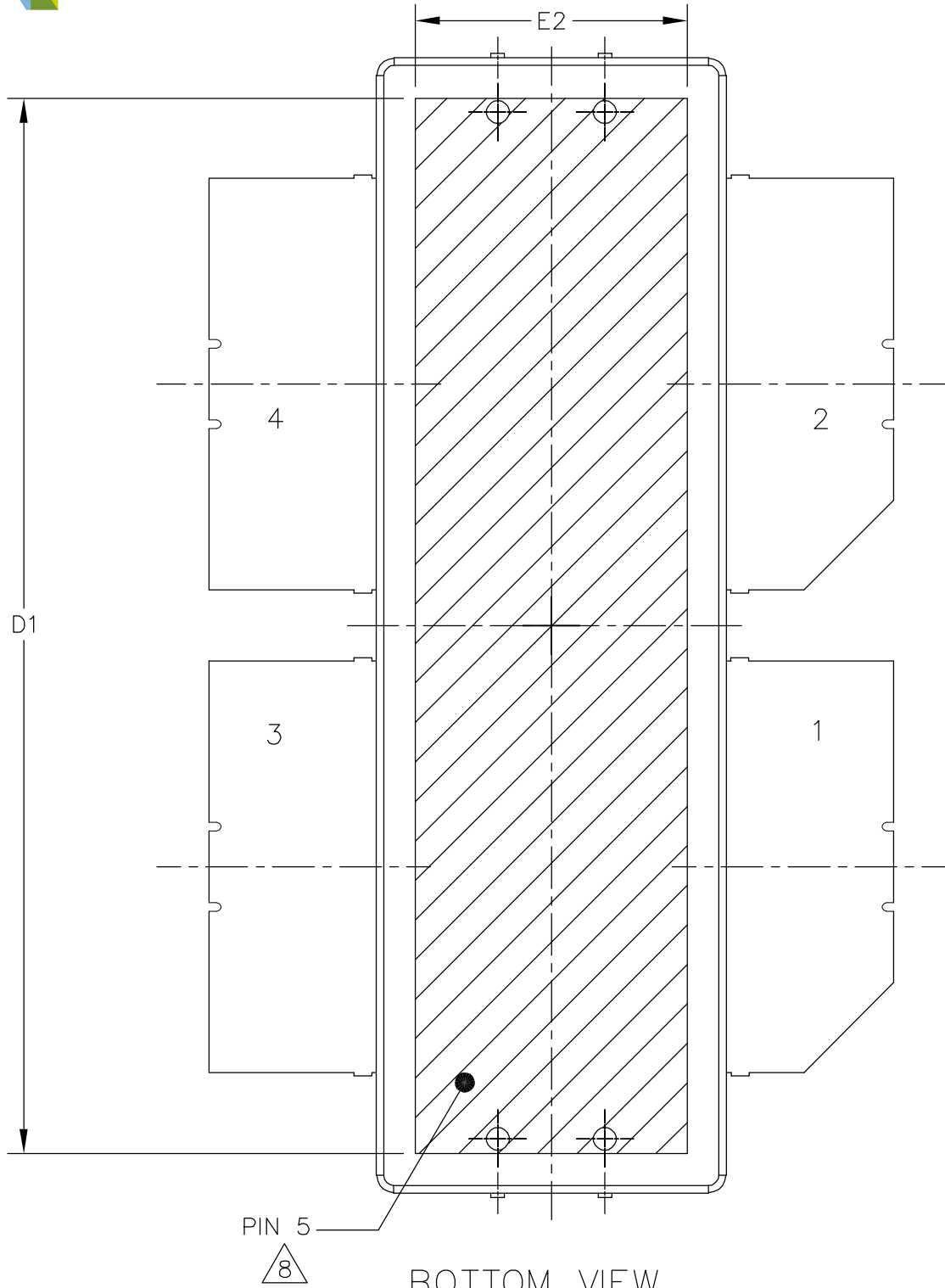


© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: OM-1230-4L	DOCUMENT NO: 98ASA00506D	REV: C
	STANDARD: NON-JEDEC	
	SOT1816-1	08 FEB 2016



BOTTOM VIEW
VIEW G-G

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: OM-1230-4L	DOCUMENT NO: 98ASA00506D REV: C	
	STANDARD: NON-JEDEC	
	SOT1816-1	08 FEB 2016



NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE H IS LOCATED AT TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS DD AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 INCH (0.15 MM) PER SIDE. DIMENSIONS DD AND E1 DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
5. DIMENSION bb DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 INCH (0.13 MM) TOTAL IN EXCESS OF THE bb DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. DATUMS A AND B TO BE DETERMINED AT DATUM PLANE H.
7. DIMENSION A1 APPLIES WITHIN ZONE J ONLY.
8. HATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG. THE DIMENSIONS D1 AND E2 REPRESENT THE VALUES BETWEEN THE TWO OPPOSITE POINTS ALONG THE EDGES OF EXPOSED AREA OF HEAT SLUG.
9. DIMPLED HOLE REPRESENTS INPUT SIDE.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
AA	.148	.152	3.76	3.86	bb	.457	.463	11.61	11.76
A1	.059	.065	1.50	1.65	c1	.007	.011	0.18	0.28
DD	1.267	1.273	32.18	32.33	e	.270 BSC		6.86 BSC	
D1	1.180	----	29.97	----	e1	.116	.124	2.95	3.15
E	.762	.770	19.35	19.56					
E1	.390	.394	9.91	10.01	aaa	.004		0.10	
E2	.306	----	7.77	----	bbb	.006		0.15	
E3	.383	.387	9.73	9.83	ccc	.010		0.25	
F	.025 BSC		0.635 BSC						

© NXP SEMICONDUCTORS N.V.
ALL RIGHTS RESERVED

MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE: OM-1230-4L	DOCUMENT NO: 98ASA00506D	REV: C
	STANDARD: NON-JEDEC	
	SOT1816-1	08 FEB 2016